



DYNAMIC ENGINEERING

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Est. 1988

Statement of Volatility

PN: PMC-BiSerial-III

Manufacturer Part Number: PMC-BiSerial-III, includes all types (-NASA1, ORB2, etc.)

Manufacturer Part Description: PMC with FPGA, FIFO options, RS485 and LVDS options, front or rear IO, PLL

Memory Type: FLASH, SRAM, FIFO

Memory Size: varies with installed FPGA and FIFO's

Volatility: SRAM and FIFO memories cleared by power cycle. FLASH is retained through power cycle. FLASH is not accessible by user for writing or read-back. FLASH is used to reload FPGA at power-on.

User Accessible: SRAM within FPGA is configured into registers etc. FPGA features are R/W [in many cases] to user software. SRAM contents are lost at power down and re-written with base design from FLASH upon power-on. External FIFO's are used to store user data during operation. All data is lost when powered down. When reset, pointers are reset making current data inaccessible. Some models do not have external FIFO's.

Clearing Procedure: Power cycle or re-write data stored contents per approved procedure. SRAM model for internal and FIFO.

Notes or Warnings: None